ADT 7900 Uno Dicing Series

(Model 7910)

7900 Uno (Model 7910)

Automatic, Single-Spindle Dicing System

Configuration
- Spindle: 2″
- Size: 8″

Features & Benefits
- **Single spindle**
- **Low cost-of-ownership**
- **Small footprint and compact (short height)**
- **High reliability**
- **Easy to use, intuitive, touch screen based GUI**
- **Easy to maintain**
- High accuracy (enhanced by advanced error mapping correction)
- Advanced vision automation
- Comprehensive, optimized dicing cycle
- Yield enhancement and cost saving capabilities
- Kerf inspection and quality analysis
- Blade wear monitoring and projection
- Spindle load monitoring
- Process data logging and statistical analysis

Optional Capabilities
- Advanced continuous magnification vision system
- Broken blade detector
- Integrated dressing station
- Variety of porous ceramic chucks (4″,5″, 6″ and 8″)
- High power spindle
- Bar code reader
- Dicing Floor Management system (DFM)

Leading Applications
- LED packages and wafers
- Silicon wafers / Discrete devices
- Power device wafers
- Glass wafers

The Ultimate Dicer for
- Universities and research institutes
- IC back-end plants (for 2″-8″ wafer dicing production lines)
- LED beginners (for process development, pilot production, R&D)
- MEC – Micro Electronic Components

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Specifications

Workpiece Size	8"
Spindle	60,000 rpm / 1.2 KW
Blade Size	2"
Y Axis	
Drive	Ball bearing lead screw
Control	Linear encoder
Resolution	0.2 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
Cutting Range	200 mm
X Axis	Air slide
Drive	Ball bearing lead screw
Feed Rate	Up to 600 mm/sec
Cutting Range	410 mm
Z Axis	
Drive	Ball bearing lead screw
Control	Rotary encoder
Resolution	0.2 µm
Repeatability	1.0 µm
Stroke	30 mm
Ø Axis	
Drive	Closed-loop, Direct-drive
Control	Linear encoder
Repeatability	4 arc-sec
Stroke	350°
Vision System	Digital camera, High bright LED illumination (vertical and oblique) Continuous digital magnification from X70 to X280 or, from X35 to X140 (optional)
Standard Features	Automatic alignment, Automatic kerf insprction, Automatic Y offset correction
User Interface	Flat 17" touch screen, Intuitive GUI (Graphic User Interface), Multilanguage support, Keyboard & Mouse (optional)
Optional	BBD (Broken Blade Detector), Barcode reader, High power spindle (2.4 KW) Dress station, DFM (Dicing Floor Management)
Utilities	
Electrical	200-240 VAC, 50/60 Hz, single phase
Air	260 L/min @ 5.5 bar
Spindle Coolant	1.1 L/min
Cutting Water	Up to 3 L/min
Dimensions	
W x D x H	875 x 975 x 1450 mm
Weight	830 Kg
Environmental	
Temperature	Typical room temperature: 20 °C - 25 °C
Humidity	< 70% (relative, non-condensing)
Floor	Floor must be vibration free

Note: *Specifications are subject to change without notice.*

ADT = Dicing
Advanced Dicing Technologies

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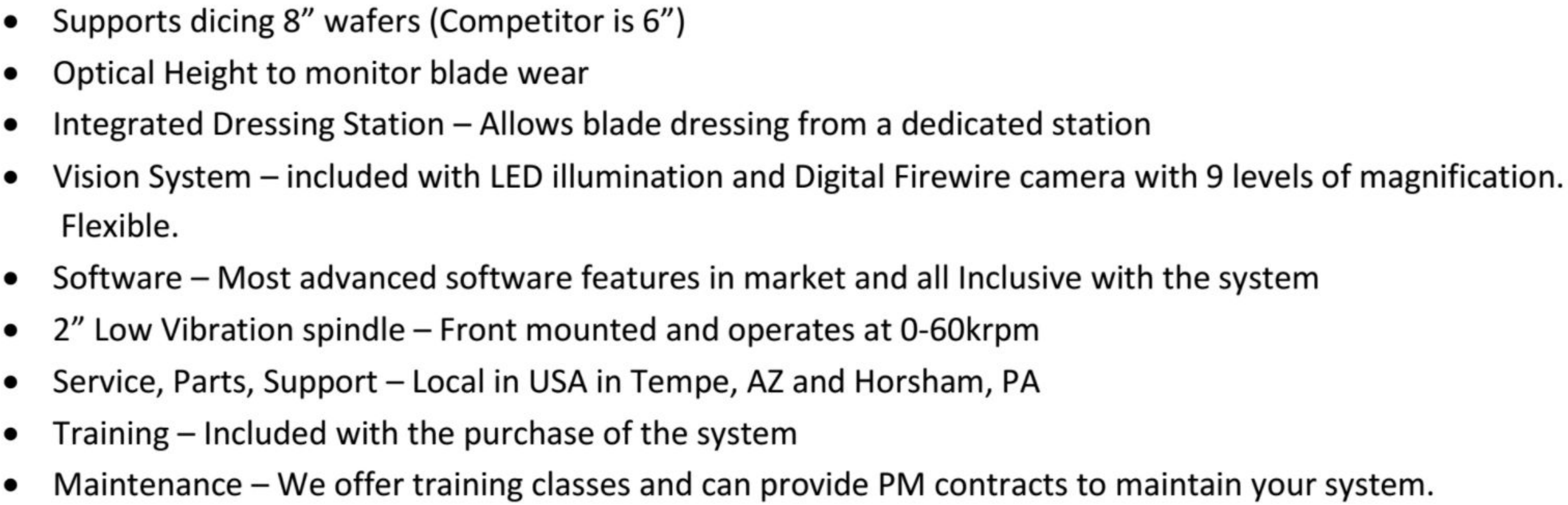
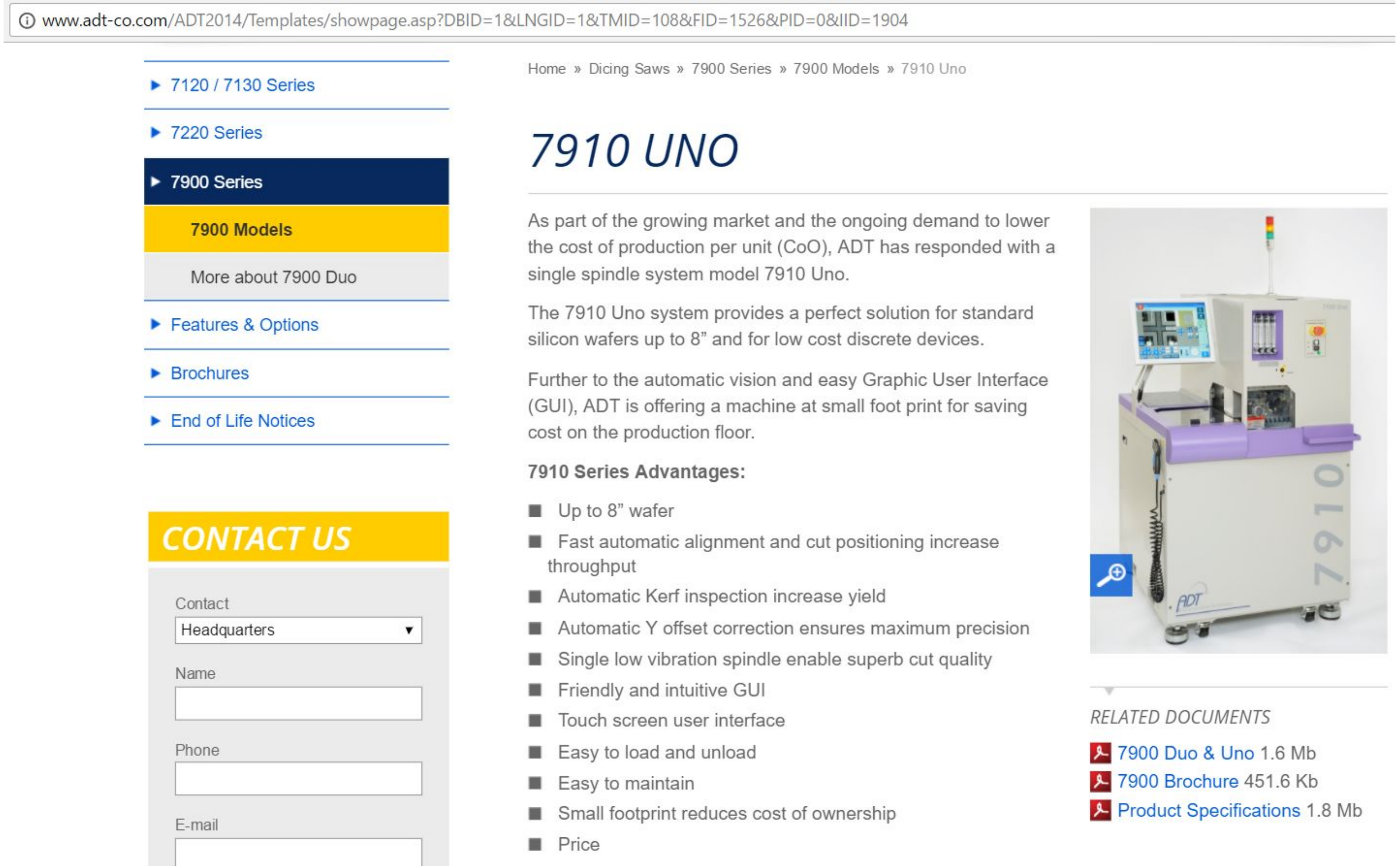


- Supports dicing 8” wafers (Competitor is 6”)
- Optical Height to monitor blade wear
- Integrated Dressing Station – Allows blade dressing from a dedicated station
- Vision System – included with LED illumination and Digital Firewire camera with 9 levels of magnification. Flexible.
- Software – Most advanced software features in market and all Inclusive with the system
- 2” Low Vibration spindle – Front mounted and operates at 0-60krpm
- Service, Parts, Support – Local in USA in Tempe, AZ and Horsham, PA
- Training – Included with the purchase of the system
- Maintenance – We offer training classes and can provide PM contracts to maintain your system.



7910 UNO

As part of the growing market and the ongoing demand to lower the cost of production per unit (CoO), ADT has responded with a single spindle system model 7910 Uno.

The 7910 Uno system provides a perfect solution for standard silicon wafers up to 8" and for low cost discrete devices.

Further to the automatic vision and easy Graphic User Interface (GUI), ADT is offering a machine at small foot print for saving cost on the production floor.

7910 Series Advantages:

- Up to 8" wafer
- Fast automatic alignment and cut positioning increase throughput
- Automatic Kerf inspection increase yield
- Automatic Y offset correction ensures maximum precision
- Single low vibration spindle enable superb cut quality
- Friendly and intuitive GUI
- Touch screen user interface
- Easy to load and unload
- Easy to maintain
- Small footprint reduces cost of ownership
- Price

RELATED DOCUMENTS

7900 Duo & Uno 1.6 Mb
7900 Brochure 451.6 Kb
Product Specifications 1.8 Mb

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Headquarters ▼

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